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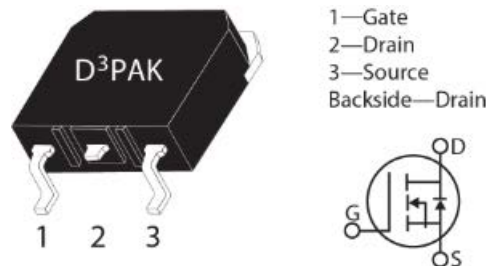
**Silicon Carbide N-Channel Power MOSFET**

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**Product Overview**

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The silicon carbide (SiC) power MOSFET product line from Microsemi increases the performance over silicon MOSFET and silicon IGBT solutions while lowering the total cost of ownership for high-voltage applications. The MSC180SMA120S device is a 1200 V, 180 mΩ SiC MOSFET in a TO-268 (D3PAK) package.

**Features**

The following are key features of the MSC180SMA120S device:

- Low capacitances and low gate charge
- Fast switching speed due to low internal gate resistance (ESR)
- Stable operation at high junction temperature,  $T_{J(max)} = 175\text{ }^{\circ}\text{C}$
- Fast and reliable body diode
- Superior avalanche ruggedness
- RoHS compliant

**Benefits**

The following are benefits of the MSC180SMA120S device:

- High efficiency to enable lighter, more compact system
- Simple to drive and easy to parallel
- Improved thermal capabilities and lower switching losses
- Eliminates the need for external freewheeling diode
- Lower system cost of ownership

**Applications**

The MSC180SMA120S device is designed for the following applications:

- PV inverter, converter, and industrial motor drives
- Smart grid transmission and distribution
- Induction heating and welding
- H/EV powertrain and EV charger
- Power supply and distribution

## 1. Device Specifications

This section shows the specifications of the MSC180SMA120S device..

### 1.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings of the MSC180SMA120S device.

**Table 1-1. Absolute Maximum Ratings**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain source voltage	1200	V
$I_D$	Continuous drain current at $T_C = 25\text{ }^\circ\text{C}$	21	A
	Continuous drain current at $T_C = 100\text{ }^\circ\text{C}$	15	
$I_{DM}$	Pulsed drain current <sup>1</sup>	40	
$V_{GS}$	Gate-source voltage	23 to -10	V
$P_D$	Total power dissipation at $T_C = 25\text{ }^\circ\text{C}$	125	W
	Linear derating factor	0.85	W/ $^\circ\text{C}$

**Note:**

1. Repetitive rating: pulse width and case temperature limited by maximum junction temperature.

The following table shows the thermal and mechanical characteristics of the MSC180SMA120S device.

**Table 1-2. Thermal and Mechanical Characteristics**

Symbol	Characteristic/Test Conditions	Min	Typ	Max	Unit
$R_{\theta JC}$	Junction-to-case thermal resistance		0.79	1.18	$^\circ\text{C}/\text{W}$
$T_J$	Operating junction temperature	-55		175	$^\circ\text{C}$
$T_{STG}$	Storage temperature	-55		150	$^\circ\text{C}$
$T_L$	Soldering temperature for 10 seconds (1.6 mm from case)			300	$^\circ\text{C}$
Wt	Package weight		0.14		oz
			4.0		g

### 1.2 Electrical Performance

The following table shows the static characteristics of the MSC180SMA120S device.  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise specified.

**Table 1-3. Static Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 100\text{ }\mu\text{A}$	1200			V
$R_{DS(on)}$	Drain-source on resistance <sup>1</sup>	$V_{GS} = 20\text{ V}, I_D = 8\text{ A}$		180	225	m $\Omega$
$V_{GS(th)}$	Gate-source threshold voltage	$V_{GS} = V_{DS}, I_D = 500\text{ }\mu\text{A}$	1.9	3.26		V

# MSC180SMA120S

## Device Specifications

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Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$\Delta V_{GS(th)}/\Delta T_J$	Threshold voltage coefficient	$V_{GS} = V_{DS}, I_D = 500 \mu A$		-5.8		mV/°C
$I_{DSS}$	Zero gate voltage drain current	$V_{DS} = 1200 V, V_{GS} = 0 V$			100	$\mu A$
		$V_{DS} = 1200 V, V_{GS} = 0 V, T_J = 125^\circ C$			500	
$I_{GSS}$	Gate-source leakage current	$V_{GS} = 20 V/-10 V$			$\pm 100$	nA

### Note:

1. Pulse test: pulse width < 380  $\mu s$ , duty cycle < 2%.

The following table shows the dynamic characteristics of the MSC180SMA120S device.  $T_J = 25^\circ C$  unless otherwise specified.

**Table 1-4. Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$C_{iss}$	Input capacitance	$V_{GS} = 0 V, V_{DD} = 1000 V, V_{AC} = 25 mV, f = 1 MHz$		510		pF	
$C_{rSS}$	Reverse transfer capacitance			4			
$C_{oss}$	Output capacitance			45			
$Q_g$	Total gate charge	$V_{GS} = -5 V/20 V, V_{DD} = 800 V, I_D = 40 A$		34		nC	
$Q_{gs}$	Gate-source charge			10			
$Q_{gd}$	Gate-drain charge			9			
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 800 V, V_{GS} = -5 V/20 V, I_D = 10 A, R_{g(ext)} = 8.0 \Omega, \text{Freewheeling diode} = \text{MSC180SMA120S} (V_{GS} = -5 V)$				ns	
$t_r$	Voltage rise time						
$t_{d(off)}$	Turn-off delay time						
$t_f$	Voltage fall time						
$E_{on}$	Turn-on switching energy			210			$\mu J$
$E_{off}$	Turn-off switching energy			23			
$t_{d(on)}$	Turn-on delay time		$V_{DD} = 800 V, V_{GS} = -5 V/20 V, I_D = 10 A, R_{g(ext)} = 8.0 \Omega, \text{Freewheeling diode} = \text{MSC010SDA120B}$				
$t_r$	Voltage rise time						
$t_{d(off)}$	Turn-off delay time						
$t_f$	Voltage fall time						
$E_{on}$	Turn-on switching energy			170		$\mu J$	
$E_{off}$	Turn-off switching energy			23			
ESR	Equivalent series resistance	$f = 1 MHz, 25 mV, \text{drain short}$			3.29		$\Omega$
SCWT	Short circuit withstand time	$V_{DS} = 960 V, V_{GS} = 20 V$				$\mu s$	
$E_{AS}$	Avalanche energy, single pulse	$V_{DS} = 150 V, I_D = 30 A$				mJ	

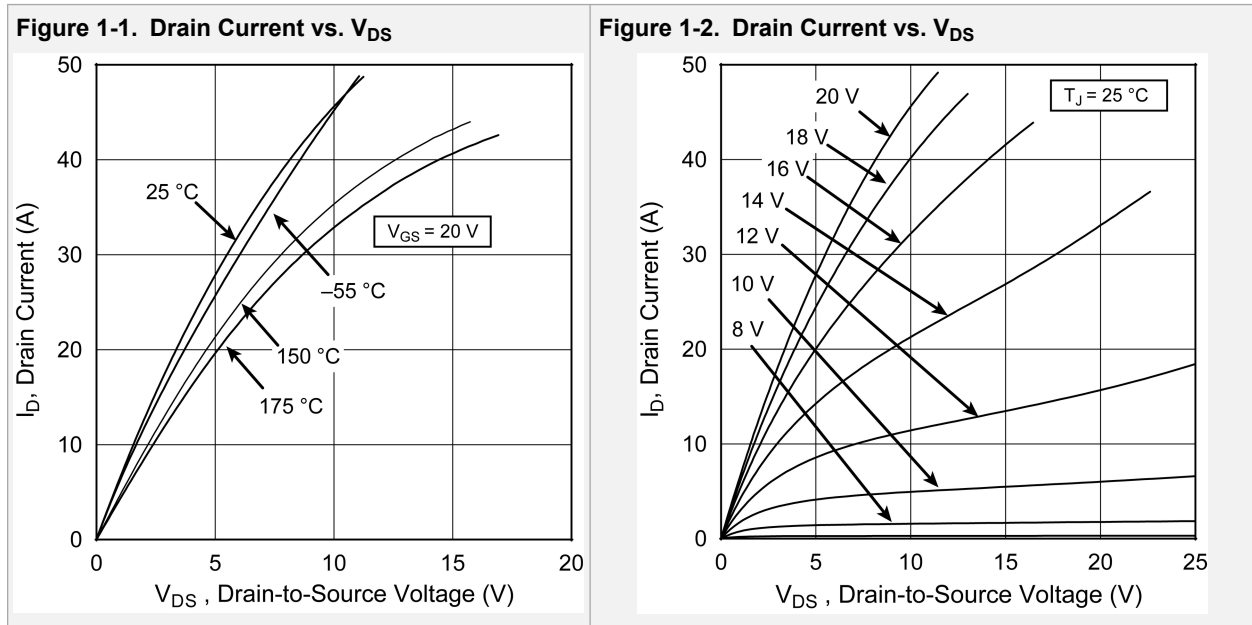
The following table shows the body diode characteristics of the MSC180SMA120S device.  $T_J = 25\text{ }^\circ\text{C}$  unless otherwise specified.

**Table 1-5. Body Diode Characteristics**

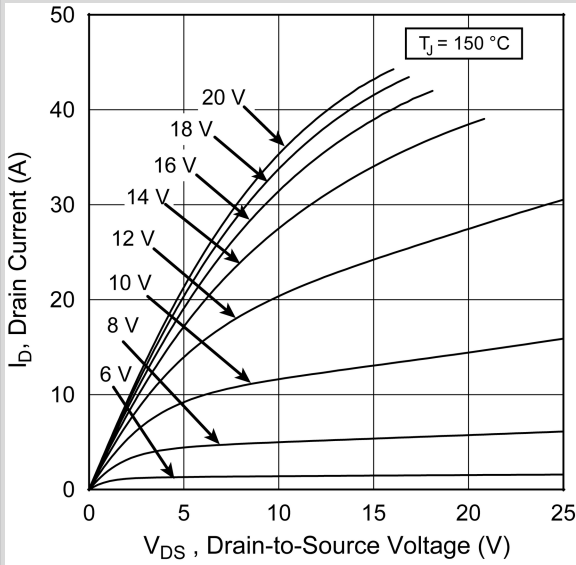
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$V_{SD}$	Diode forward voltage	$I_{SD} = 0\text{ V}, V_{GS} = 0\text{ V}$		3.81		V
		$I_{SD} = 0\text{ V}, V_{GS} = -5\text{ V}$		3.96		
$t_{rr}$	Reverse recovery time	$I_{SD} = 10\text{ A}, V_{GS} = -5\text{ V}, V_{DD} = 800\text{ V}, dl/dt = -1120\text{ A}/\mu\text{s}, \text{ Drive } R_g = 8\ \Omega$		28		ns
$Q_{rr}$	Reverse recovery charge			88		nC
$I_{RRM}$	Reverse recovery current				4.2	

### 1.3 Typical Performance Curves

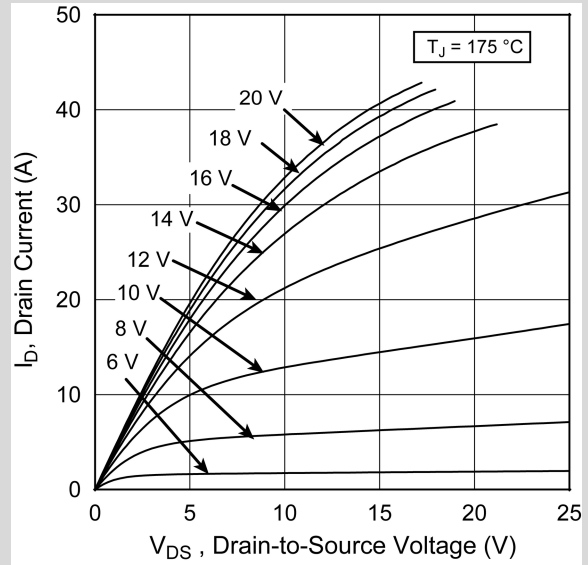
This section shows the typical performance curves of the MSC180SMA120S device.



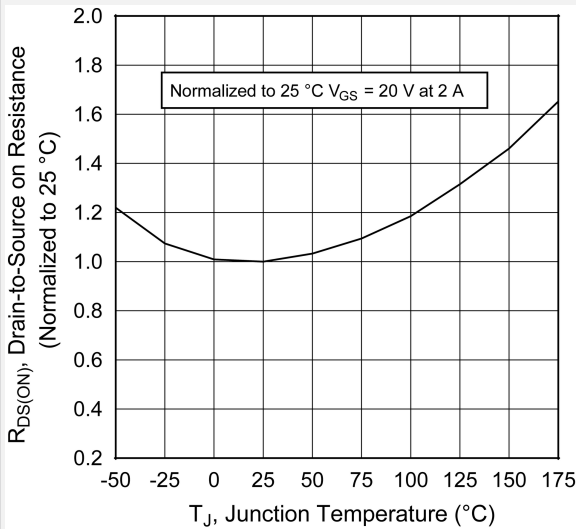
**Figure 1-3. Drain Current vs.  $V_{DS}$**



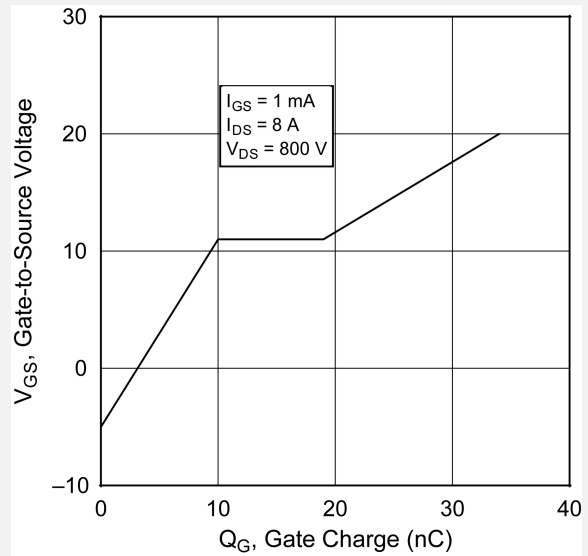
**Figure 1-4. Drain Current vs.  $V_{DS}$**



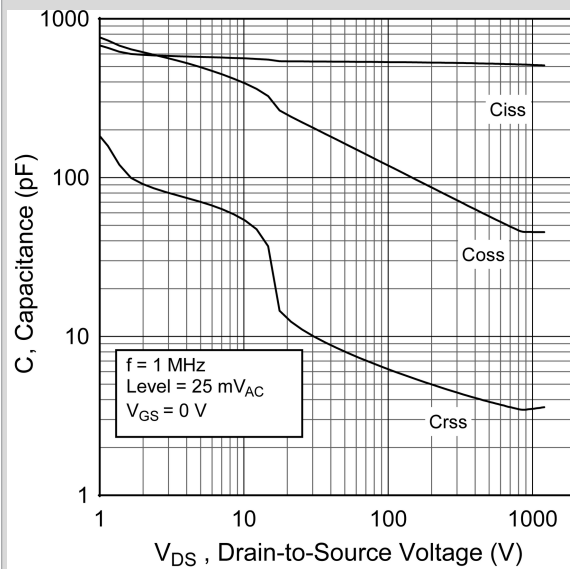
**Figure 1-5.  $R_{DS(on)}$  vs. Junction Temperature**



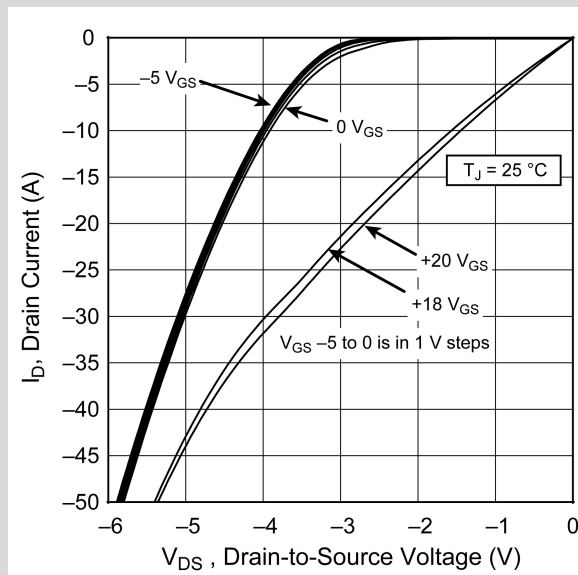
**Figure 1-6. Gate Charge Characteristics**



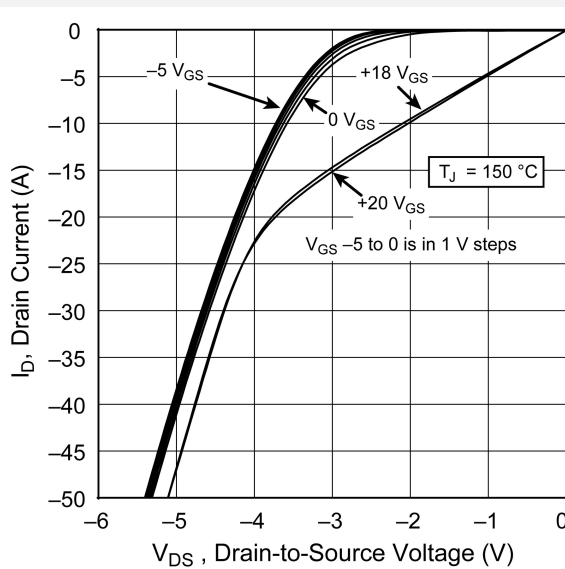
**Figure 1-7. Capacitance vs. Drain-to-Source Voltage**



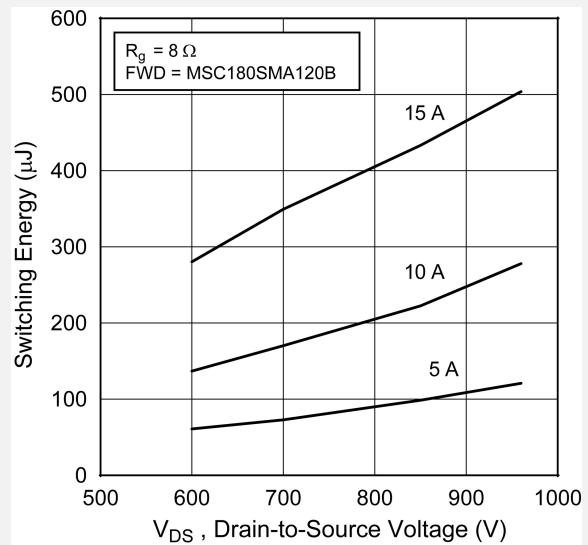
**Figure 1-8.  $I_D$  vs.  $V_{DS}$  3<sup>rd</sup> Quadrant Conduction**



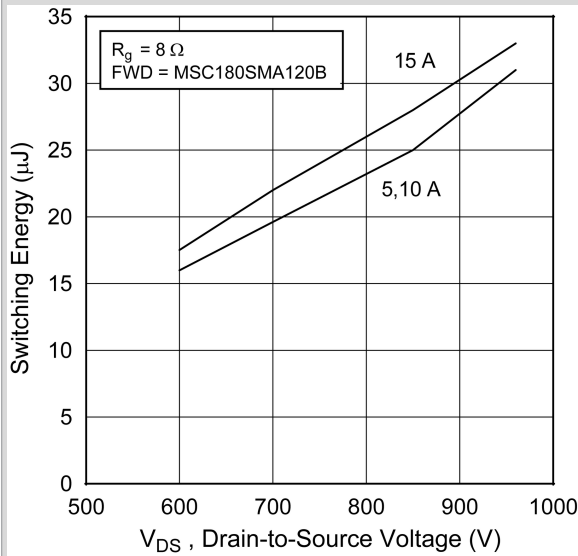
**Figure 1-9.  $I_D$  vs.  $V_{DS}$  3<sup>rd</sup> Quadrant Conduction**



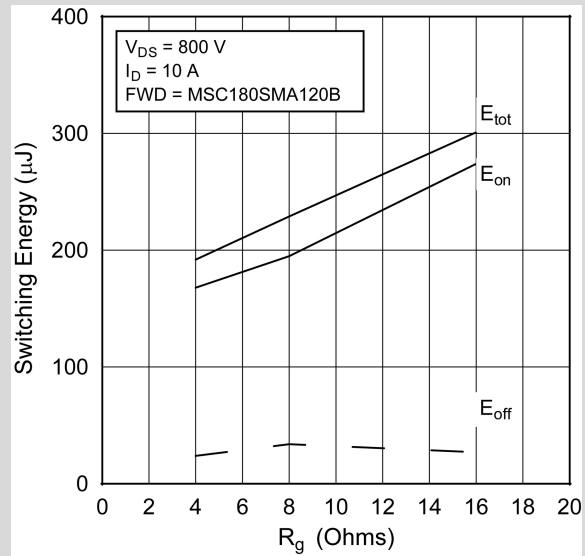
**Figure 1-10. Switching Energy  $E_{on}$  vs.  $V_{DS}$  &  $I_D$**



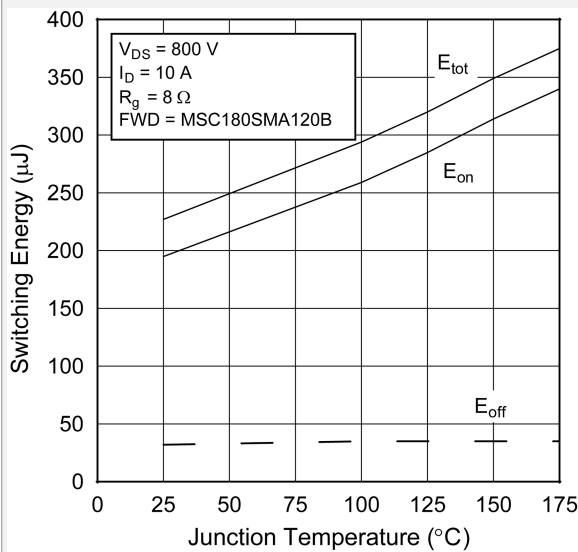
**Figure 1-11. Switching Energy E<sub>off</sub> vs. V<sub>DS</sub> & I<sub>D</sub>**



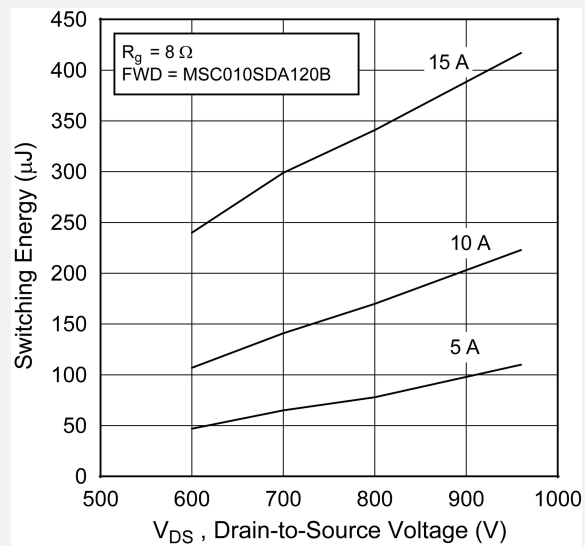
**Figure 1-12. Switching Energy vs. R<sub>g</sub>**



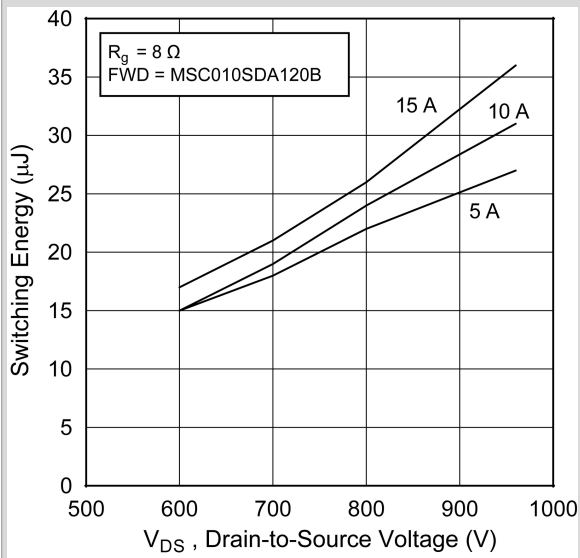
**Figure 1-13. Switching Energy vs. Temperature**



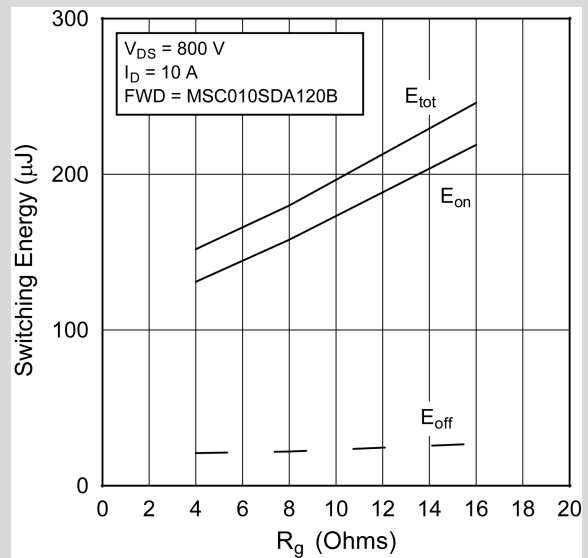
**Figure 1-14. Switching Energy E<sub>on</sub> vs. V<sub>DS</sub> & I<sub>D</sub>**



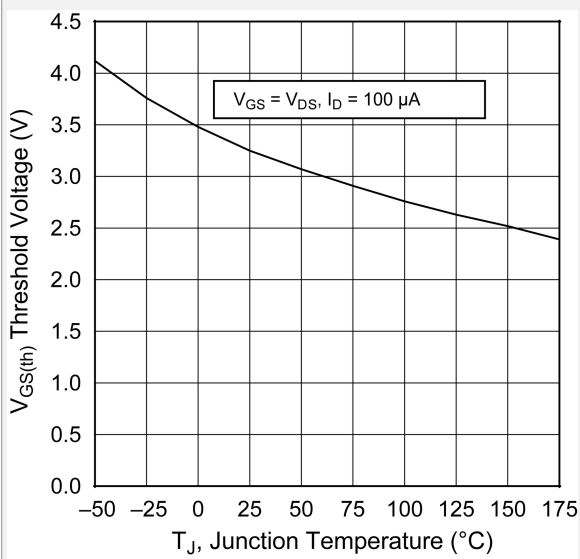
**Figure 1-15. Switching Energy E<sub>off</sub> vs. V<sub>DS</sub> & I<sub>D</sub>**



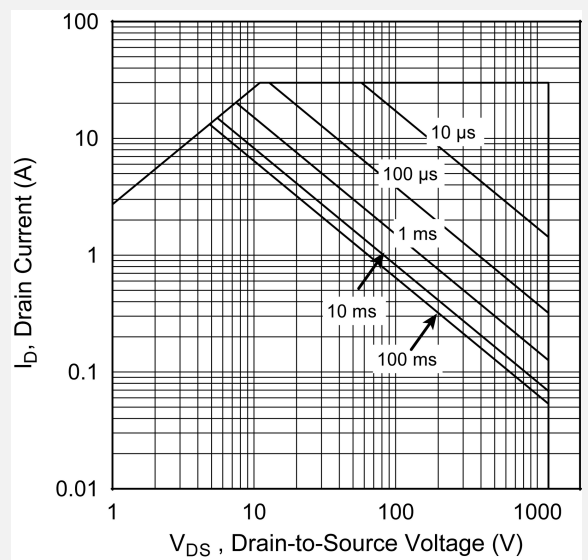
**Figure 1-16. Switching Energy vs. R<sub>g</sub>**



**Figure 1-17. Threshold Voltage vs. Junction Temp.**

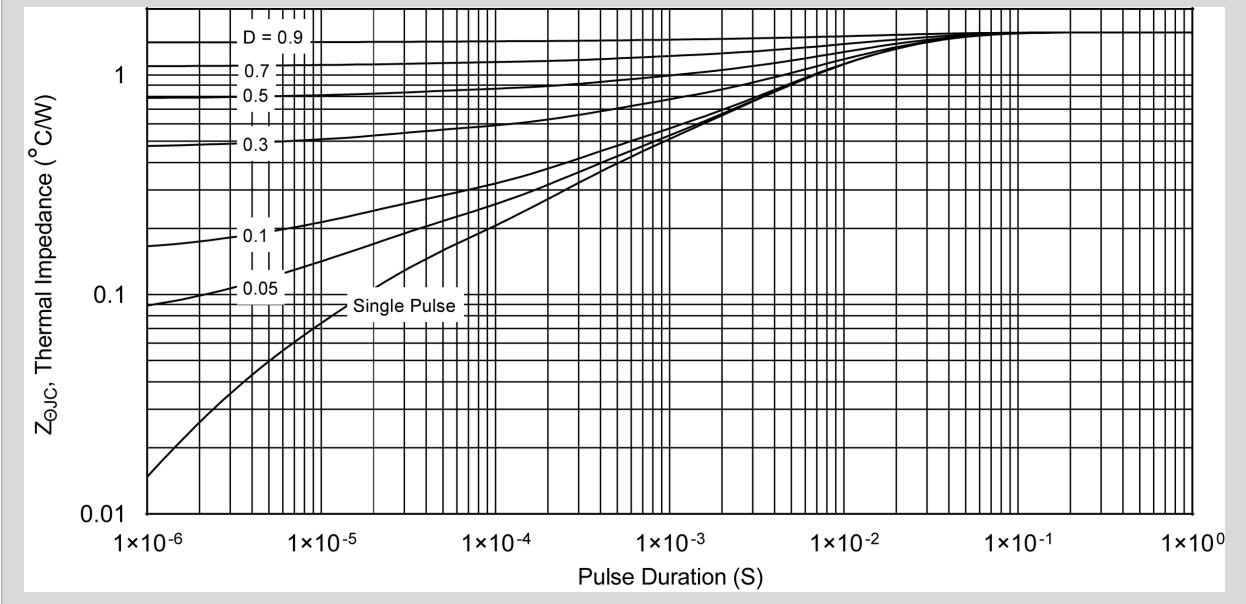


**Figure 1-18. Forward Safe Operating Area**



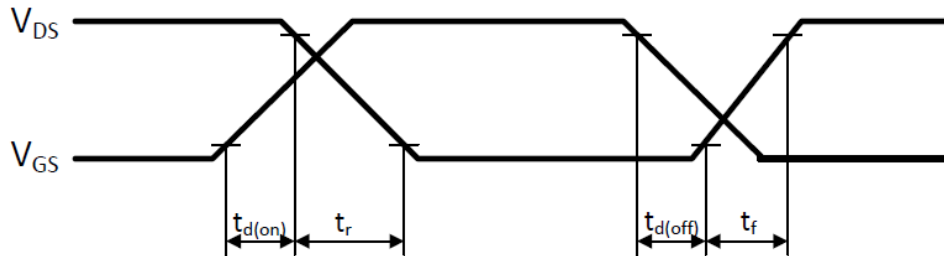


**Figure 1-19. Maximum Transient Thermal Impedance**



The following figure shows the switching waveform diagram of the MSC180SMA120S device.

**Figure 1-20. Switching Waveform**



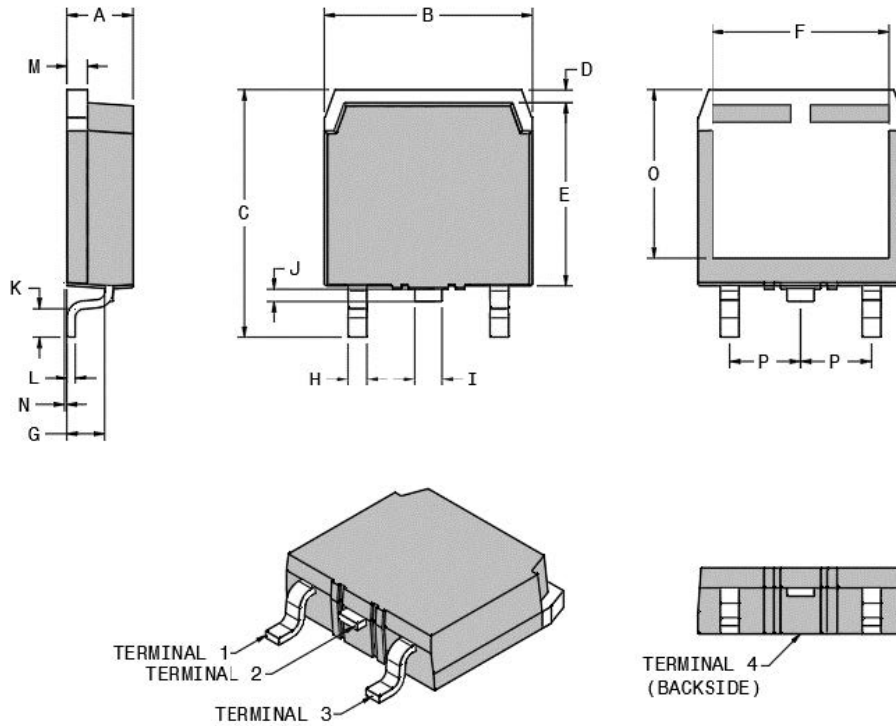
## 2. Package Specification

This section shows the package specification of the MSC180SMA120S device.

### 2.1 Package Outline Drawing

The following figure illustrates the TO-268 package outline of the MSC180SMA120S device.

**Figure 2-1. Package Outline Drawing**



The following table shows the TO-268 dimensions and should be used in conjunction with the package outline drawing.

**Table 2-1. TO-268 Dimensions**

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
A	4.90	5.10	0.193	0.201
B	15.85	16.20	0.624	0.638
C	18.70	19.10	0.736	0.752
D	1.00	1.025	0.039	0.049
E	13.80	14.00	0.543	0.551
F	13.30	13.60	0.524	0.535
G	2.70	2.90	0.106	0.114
H	1.15	1.45	0.045	0.057
I	1.95	2.21	0.077	0.087

# MSC180SMA120S

## Package Specification

.....continued

Symbol	Min (mm)	Max (mm)	Min (in.)	Max (in.)
J	0.94	1.40	0.037	0.055
K	2.40	2.70	0.094	0.106
L	0.40	0.60	0.016	0.024
M	1.45	1.60	0.057	0.063
N	0.00	0.018	0.00	0.007
O	12.40	12.70	0.488	0.500
P	5.45 BSC (nom.)		0.215 BSC (nom.)	
Terminal 1	Gate			
Terminal 2	Drain			
Terminal 3	Source			
Terminal 4	Drain			

### 3. **Revision History**

**Table 3-1. Revision History**

<b>Revision</b>	<b>Date</b>	<b>Description</b>
A	03/2021	Document created.

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